

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	311	(data adj collection or data adj collected) and (real adj time or in adj situ) and wafer and process and recipe	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/07 18:23
S2	189	sensor and S1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/17 10:20
S3	245	alvi.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/17 10:20
S4	64	control and S3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/17 10:20
S5	2	("5081421").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 06:48
S6	131	("5081421").URPN.	USPAT	OR	ON	2005/02/08 06:48
S7	22	("20020093648" "20020097406" "20020102749" "20020103564" "20020106848" "20020107650" "4632561" "4750822" "4854710" "4933635" "5023561" "5073755" "5081421" "5182452" "5528153" "5952674" "6020264" "6054868" "6136615" "6281024" "6407386" "H000589").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/08 06:50
S8	6	("5952674").URPN.	USPAT	OR	ON	2005/02/08 06:55
S9	2348	(cmp or chemical adj mechanical adj polishing) and (real adj time or realtime)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 08:38
S10	205	recipe and program and S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 07:35

S11	2	("6656023").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 08:00
S12	2	("6293851").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 08:38
S13	1169	(700/121).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 08:45
S14	45	(cmp or chemical adj mechanical adj polishing) and (real adj time or realtime) and S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 08:46
S15	330	(700/31).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 08:47
S16	2	(cmp or chemical adj mechanical adj polishing) and (real adj time or realtime) and S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 08:47
S17	293	(700/45).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 08:47
S18	2	(cmp or chemical adj mechanical adj polishing) and (real adj time or realtime) and S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 08:47

S19	283	(700/44).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 08:47
S20	2	(cmp or chemical adj mechanical adj polishing) and (real adj time or realtime) and S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 08:48